

ABSTRACT

The invention relates to an equipment for semiconductor production, in particular to a heat treatment apparatus. The apparatus comprises a cooling unit (200), a heating unit (300) and a transmission unit (400). The cooling unit (200) comprises a cooling plate (210) for cooling a substrate (w), and the heating unit (300) comprises a heating plate (310) for heating the substrate (w). The transmission unit (400) comprises a transmission arm (410), a lifting module and a linear module. The transmission arm (410) supports the substrate (w) and transmits the substrate (w) between the cooling unit (200) and the heating unit (300). The transmission arm (410) is disposed on the lifting module, and the lifting module drives the transmission arm (410) to ascend and descend. The linear module drives the transmission arm (410) to transmit the substrate (w) between the cooling plate (210) and the heating plate (310). The internal space of the apparatus is optimized.